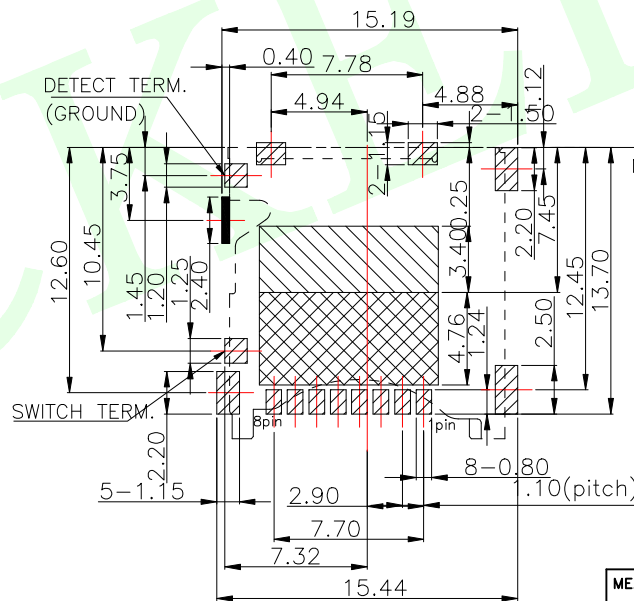
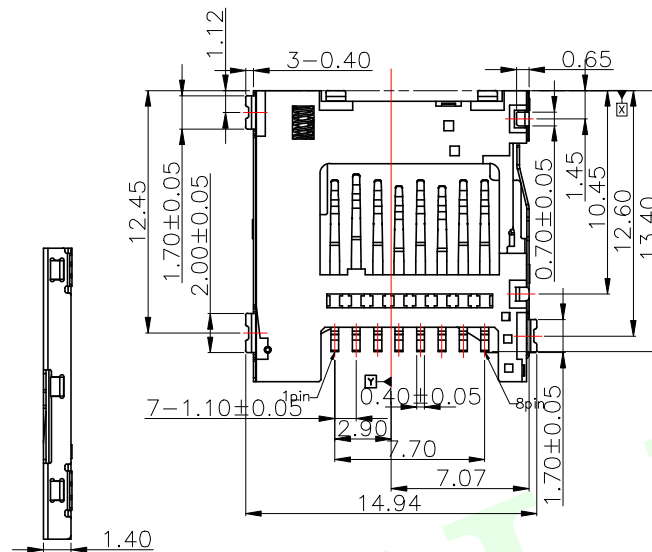
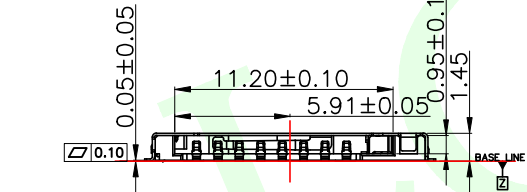
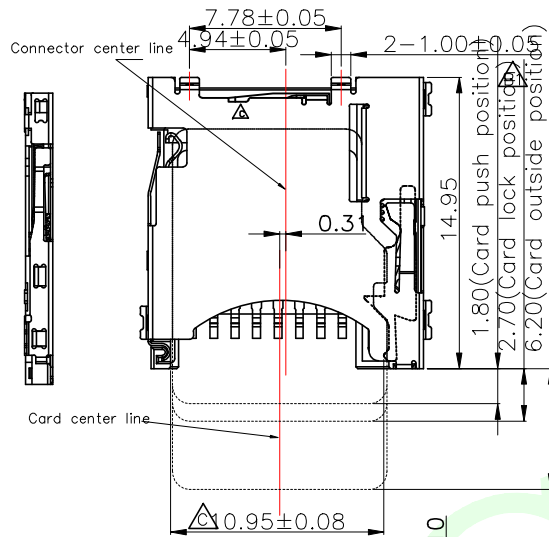
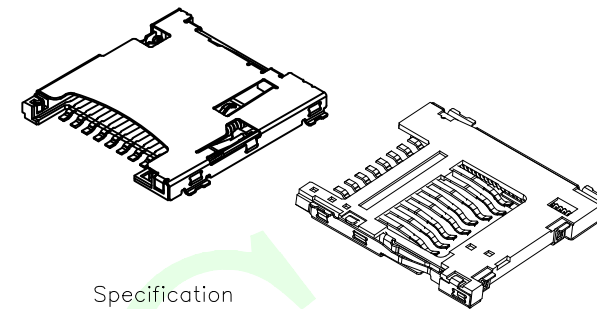
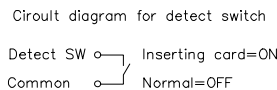
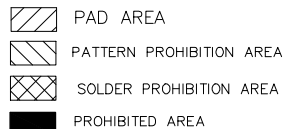


RoHS Compliant



RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)



Specification

1.MATERIAL:

- 1.1 Insulator:High Temperature Thermoplastic, (LCP,MG350),UL Black 94V-0.
- 1.2 Contact: Phosphor Bronze(C5210R-H,T=0.15±0.03mm)
- 1.3 Shell: SUS304-H T=0.12±0.03mm

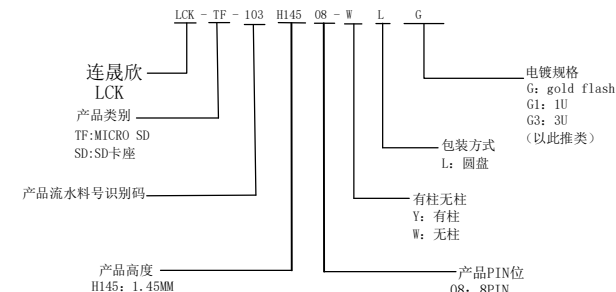
2.Plating:

- 2.1 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 100u"min Sn over Ni on solder area
- 2.2 Shell: Plated 50u"min Ni Overall
Plated 1u"min Au Selective Contact Area

3.Property:

- 3.1 Current Rating :0.5A AC/DC max.
- 3.2 Voltage Rating :3.3V/5V(AC/DC)
- 3.3 Contact Resistance:Contact Pin 100mΩ max.
- 3.4 Insert/Pulling Force: 40N Max / 0.5~40N
- 3.5 Smt Solder Temperature: Should Under 260°C
- 3.6 Operation Temperature Range: -40~+85°C

产品采购完整示号: LCK-TF-103H14508-WLG



PIN	T/F CARD
	microSD
8	P8 Dat1
7	P7 Dat0
6	P6 VSS
5	P5 CLK
4	P4 VDD
3	P3 CMD
2	P2 CD/Dat3
1	P1 Dat2

MEASURE POINT:
QUADRANT POINT (QP)
TANGENCY POINT (TP)
INTERSECTION POINT (IP)

UNLESS OTHERWISE
SPECIFIED,TOLERANCE:
X. ±0.25
X.x ±0.20
X.xx ±0.15
ANGULAR ±3°

联晟欣连接器(深圳)有限公司
Lianshengxin Connector (Shenzhen) Co., Ltd

DESIGN	Andy	DATE	2014.12.24	TITLE: MICRO SD TF卡座1.45H SMT		
CHECKED		DATE				
APPROVED		DATE				
PART NO: LCK-TF-103H14508-WLG				REV: 04	SCALE: 1:1	UNIT: mm
DRAWING NO:102022035				SIZE: A4	SHEET: 1/1	